

RoHS Compliant Product  
A suffix of "-C" specifies halogen & lead-free

## DESCRIPTION

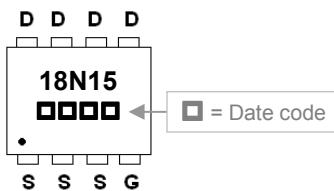
The SPR18N15-C is the highest performance trench N-Ch MOSFETs with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The SPR18N15-C meet the RoHS and Green Product requirement with full function reliability approved.

## FEATURES

- Advanced High Cell Density Technology
- Super Low Gate Charge

## MARKING



## PACKAGE INFORMATION

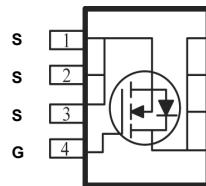
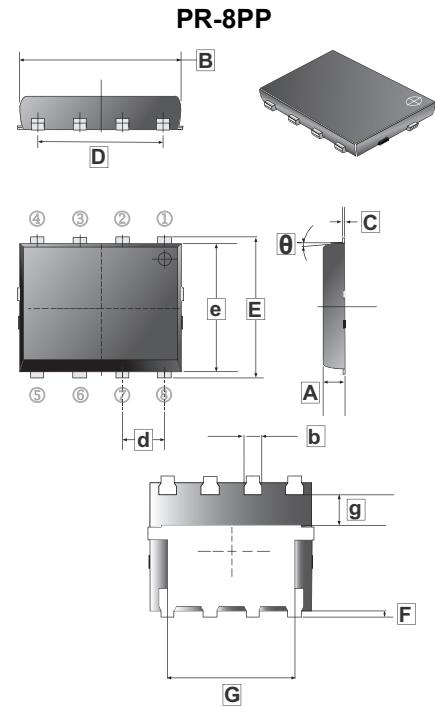
Package	MPQ	Leader Size
PR-8PP	3K	13 inch

## ORDER INFORMATION

Part Number	Type
SPR18N15-C	Lead (Pb)-free and Halogen-free

## ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	150	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, @ $V_{GS}=10V$ <sup>1</sup>	$I_D$	18	A
		11.4	
		4	
		3.2	
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	72	A
Maximum Power Dissipation <sup>1</sup>	$P_D$	50	W
		20	
		2.5	
		1.6	
Operating Junction & Storage Temperature	$T_J, T_{STG}$	-55~150	°C
Thermal Resistance Ratings			
Thermal Resistance Junction-Ambient <sup>1</sup> (Max).	$R_{\theta JA}$	$t \leq 10s, 50$	°C/W
		Steady State, 83	
Thermal Resistance Junction-Ambient (Max).		125	
Thermal Resistance Junction-Case <sup>1</sup> (Max).	$R_{\theta JC}$	2.5	



REF.	Millimeter Min.	Millimeter Max.	REF.	Millimeter Min.	Millimeter Max.
A	0.9	1.1	$\theta$	0°	12°
B	4.9	5.1	b	0.33	0.51
C	0.2	0.3	d	1.27	BSC
D	3.81	4	e	5.7	5.9
E	5.95	6.2	g	1.1	1.4
F	0.1	0.2			
G	3.81	4			

**ELECTRICAL CHARACTERISTICS** (T<sub>J</sub>=25°C unless otherwise specified)

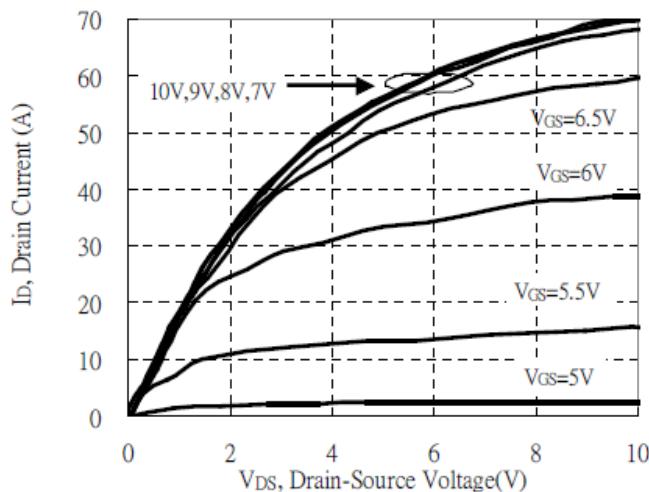
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	150	-	-	V	V <sub>GS</sub> =0, I <sub>D</sub> =250μA
Gate-Threshold Voltage	V <sub>GS(th)</sub>	2	-	4	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
Gate-Source Leakage Current	I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> = ±20V
Drain-Source Leakage Current	I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =120V, V <sub>GS</sub> =0
		-	-	25		V <sub>DS</sub> =120V, V <sub>GS</sub> =0
		-	55	70	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =15A
Static Drain-Source On-Resistance <sup>3</sup>		R <sub>DS(ON)</sub>	-	65		V <sub>GS</sub> =7V, I <sub>D</sub> =10A
Total Gate Charge	Q <sub>g</sub>	-	20	-	nC	I <sub>D</sub> =15A V <sub>DS</sub> =80V V <sub>GS</sub> =10V
Gate-Source Charge	Q <sub>gs</sub>	-	5.5	-		
Gate-Drain Change	Q <sub>gd</sub>	-	7	-		
Turn-on Delay Time	T <sub>d(on)</sub>	-	6	-	nS	V <sub>DD</sub> =80V I <sub>D</sub> =10A V <sub>GS</sub> =10V R <sub>G</sub> =3Ω
Rise Time	T <sub>r</sub>	-	5	-		
Turn-off Delay Time	T <sub>d(off)</sub>	-	13	-		
Fall Time	T <sub>f</sub>	-	6	-		
Input Capacitance	C <sub>iss</sub>	-	1274	-	pF	V <sub>GS</sub> =0 V <sub>DS</sub> =30V f=1MHz
Output Capacitance	C <sub>oss</sub>	-	117	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	49	-		
<b>Source-Drain Diode</b>						
Continuous Source Current <sup>1</sup>	I <sub>s</sub>	-	-	18	A	
Pulsed Source Current <sup>2</sup>	I <sub>SM</sub>	-	-	72	A	
Diode Forward Voltage <sup>3</sup>	V <sub>SD</sub>	-	-	1.2	V	V <sub>GS</sub> =0, I <sub>s</sub> =10A, T <sub>J</sub> =25°C
Reverse Recovery Time	t <sub>rr</sub>	-	30	-	nS	I <sub>F</sub> =10A, dI/dt=100A/μs, T <sub>J</sub> =25°C
Reverse Recovery Charge	Q <sub>rr</sub>	-	100	-	nC	

Notes:

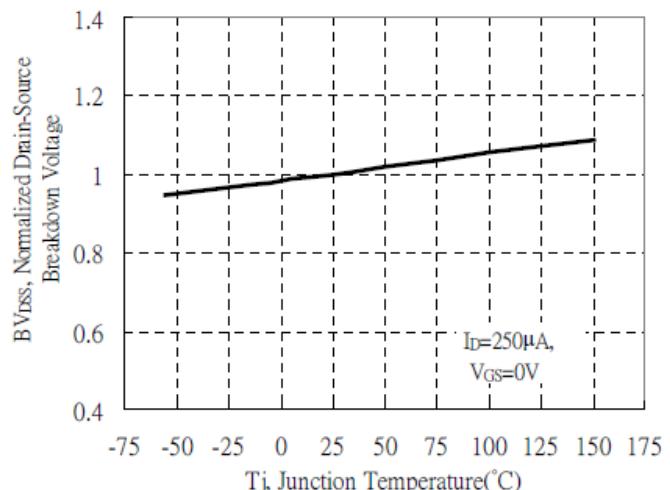
1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The power dissipation is limited by 150°C junction temperature.
3. The data tested by pulsed, pulse width ≤300μs, duty cycle≤2%.

## CHARACTERISTIC CURVES

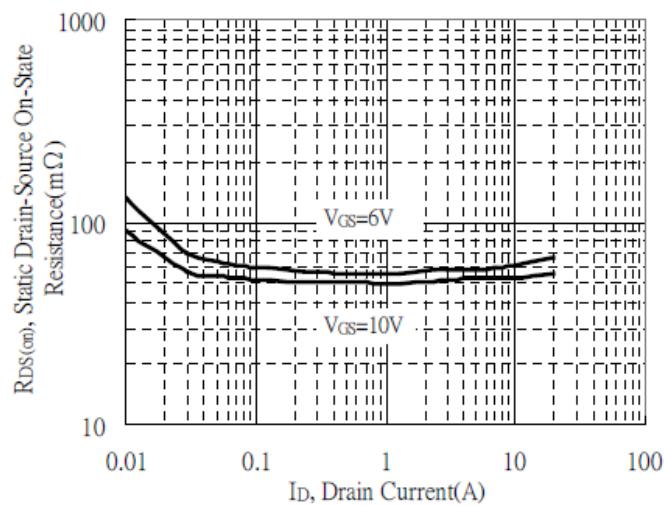
Typical Output Characteristics



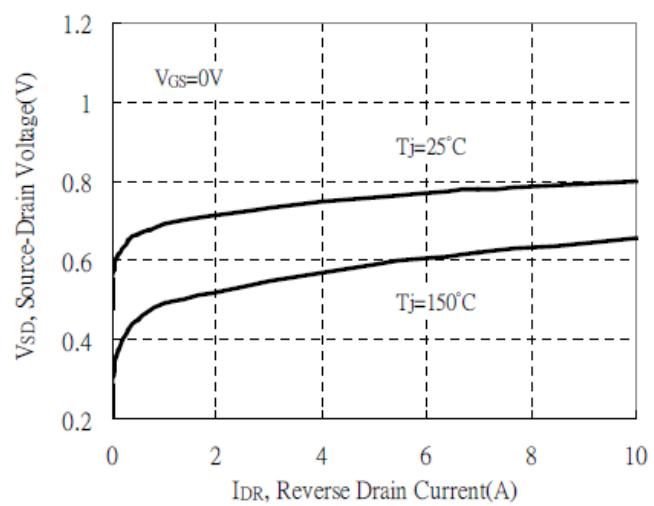
Breakdown Voltage vs Ambient Temperature



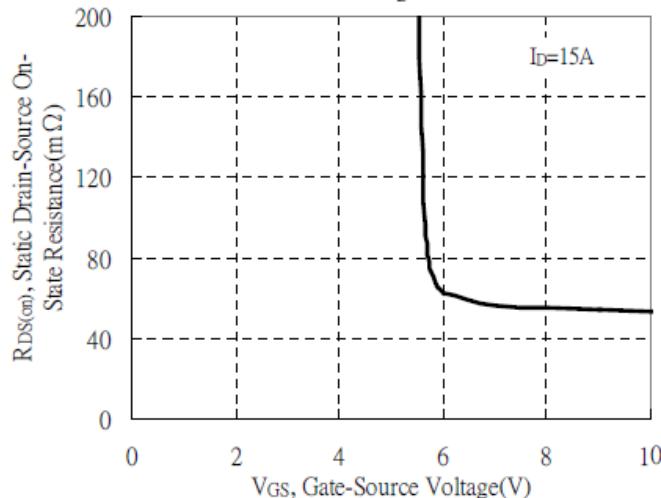
Static Drain-Source On-State resistance vs Drain Current



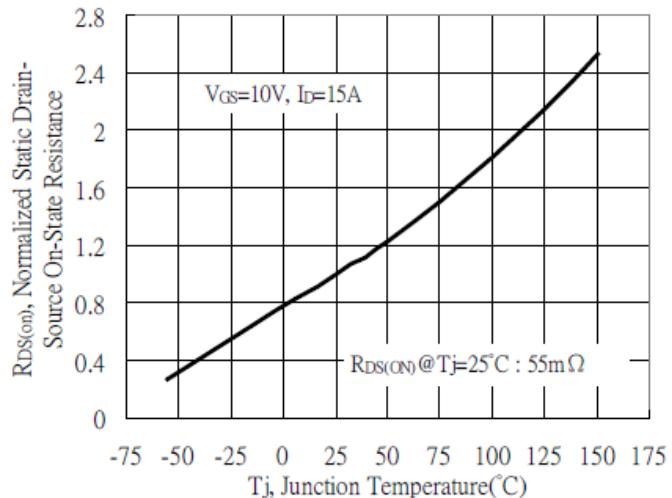
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

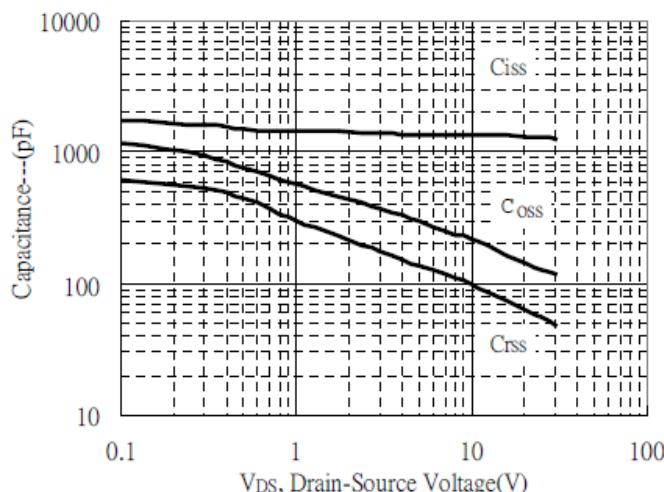


Drain-Source On-State Resistance vs Junction Temperature

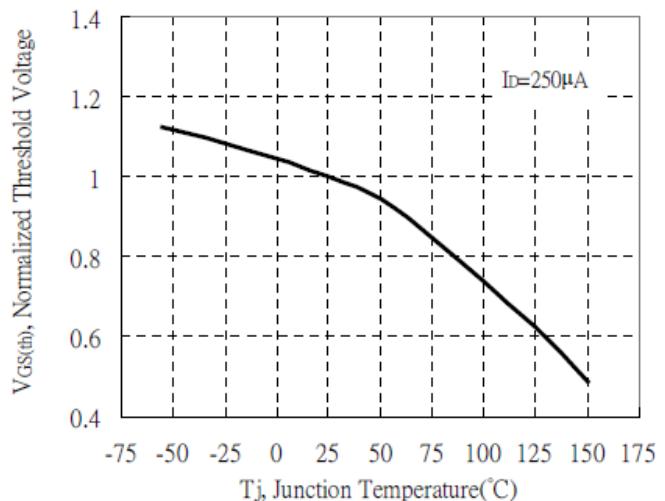


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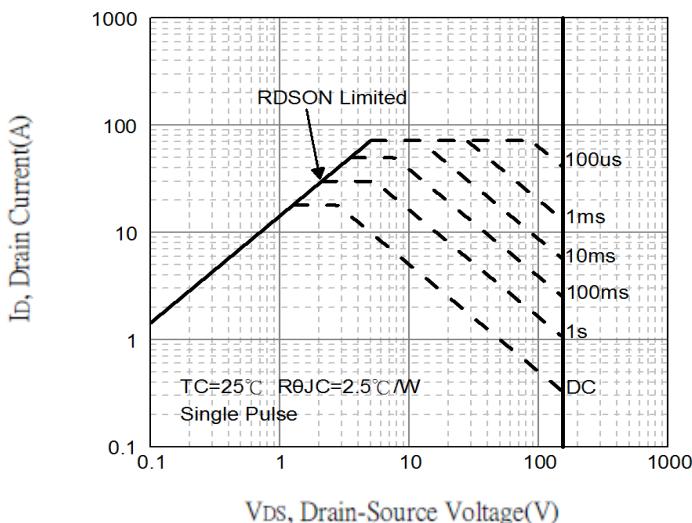
Capacitance vs Drain-to-Source Voltage



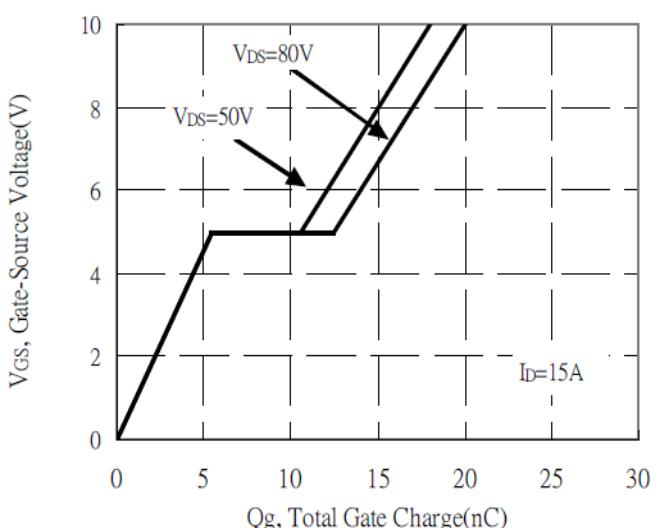
Threshold Voltage vs Junction Temperature



Maximum Safe Operating Area



Gate Charge Characteristics



Transient Thermal Response Curves

